# Monthly LabAdviser update: 2/1 2013

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| Updated Subject  | Contributer | Link to the update pages |
| **LPCVD nitride** | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Thin film deposition/Furnace LPCVD Nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_Nitride) |
| LPCVD TEOS | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Thin film deposition/Deposition of Silicon Oxide/Deposition of Silicon Oxide using LPCVD TEOS](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide/Deposition_of_Silicon_Oxide_using_LPCVD_TEOS) |
| **Furnace LPCVD P-Si** | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Thin film deposition/Furnace LPCVD PolySilicon](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_PolySilicon) |
| **Furnace P pre-dep** | Pernille V. Larsen @ danchip | [Specific Process Knowledge/Thermal Process/A4 Furnace Phosphorus pre-dep](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/A4_Furnace_Phosphorus_pre-dep) |
| **Furnace B pre-dep** | Pernille V. Larsen @ danchip | [Specific Process Knowledge/Thermal Process/A2 Furnace Boron pre-dep](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/A2_Furnace_Boron_pre-dep) |
| Furnace B drive-in | **Pernille V. Larsen @ danchip** | [Specific Process Knowledge/Thermal Process/A1 Furnace Boron drive-in](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/A1_Furnace_Boron_drive-in) |
| **Furnace noble** | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Thermal Process/Furnace Noble](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thermal_Process/Furnace_Noble) |
| **Black Magic PECVD**OverviewDetailsgraphene | **KN** | [Specific Process Knowledge/Thin film deposition/Black Magic PECVD](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Black_Magic_PECVD)[Specific Process Knowledge/Thin film deposition/Black Magic PECVD/Black Magic details](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Black_Magic_PECVD/Black_Magic_details&rcid=7782)[Specific Process Knowledge/Thin film deposition/Black Magic PECVD/Graphene](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Thin_film_deposition/Black_Magic_PECVD/Graphene&rcid=7823) |
| **Probe station** | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Characterization/Probe station](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Characterization/Probe_station&rcid=7879) |
| 4-point probe | Mikkel D. Mar@ danchip | [Specific Process Knowledge/Characterization/4-Point Probe](http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Characterization/4-Point_Probe&rcid=7791) |
| **SEM’s** | Jonas M. Lindhard @ danchip | [Specific Process Knowledge/Characterization/SEM: Scanning Electron Microscopy](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/SEM%3A_Scanning_Electron_Microscopy) |
| **New equipment in pipeline** | Berit G. Herstrøm @ danchip | [New equipment in the pipeline](http://labadviser.danchip.dtu.dk/index.php/New_equipment_in_the_pipeline) |
| **Old equipment for decommissioning** | Berit G. Herstrøm @ danchip | [Old equipment for decommissioning](http://labadviser.danchip.dtu.dk/index.php/Old_equipment_for_decommissioning) |
| **LabAdviser monthly updates** can be found in LabAdviser | Berit G. Herstrøm @ danchip | [LabAdviser/LabAdviser Updates](http://labadviser.danchip.dtu.dk/index.php/LabAdviser/LabAdviser_Updates) |
| **Resist spinners** | Elena Khomtchenko @ danchip | [Specific Process Knowledge/Photolithography/Photoresist Spinners](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Photolithography/Photoresist_Spinners) |
| **Resist processes** | Elena Khomtchenko @ danchip | [Specific Process Knowledge/Photolithography/AZ5214E standard resist - positive process](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Photolithography/AZ5214E_standard_resist_-_positive_process)[Specific Process Knowledge/Photolithography/AZ5214E standard resist - reverse process](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Photolithography/AZ5214E_standard_resist_-_reverse_process)[Specific Process Knowledge/Photolithography/AZ5214E diluted resist - positive process](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Photolithography/AZ5214E_diluted_resist_-_positive_process) |
| **E-beam** | Tina Greibe @ danchip | [Specific Process Knowledge/E-beam lithography](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/E-beam_lithography) |
| **DRIE-Pegasus**Nanoetch | Jonas M. Lindhard @ danchip | [Specific Process Knowledge/Etch/DRIE-Pegasus](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus)[Specific Process Knowledge/Etch/DRIE-Pegasus/nanobosch/nanobosch6](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/nanobosch/nanobosch6)[Specific Process Knowledge/Etch/DRIE-Pegasus/nanobosch/nb-1.0](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/nanobosch/nb-1.0)[Specific Process Knowledge/Etch/DRIE-Pegasus/Parameters](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/Parameters)[Specific Process Knowledge/Etch/DRIE-Pegasus/nanoetch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/DRIE-Pegasus/nanoetch) |
| **IBSD Ionfab**Deposition of SiO2Deposition of TiO2 | Berit G. Herstrøm @ danchip | [Specific Process Knowledge/Thin film deposition/Deposition of Silicon Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide)[Specific Process Knowledge/Specific Process Knowledge/Thin film deposition/Deposition of Silicon Oxide /IBSD of SiO2](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide_/IBSD_of_SiO2)[Specific Process Knowledge/Thin film deposition/Deposition of Titanium Oxide](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Titanium_Oxide)[Specific Process Knowledge/Etch/IBE⁄IBSD Ionfab 300](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/IBE%E2%81%84IBSD_Ionfab_300) |
| **IBE Ionfab Si etch** | Kristian H. Rasmussen @ Nanotech | [Specific Process Knowledge/Etch/IBE⁄IBSD Ionfab 300/IBE Si etch](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/IBE%E2%81%84IBSD_Ionfab_300/IBE_Si_etch) |
| **ASE** | Jonas M. Lindhard @ danchip | [Specific Process Knowledge/Etch/ASE (Advanced Silicon Etch)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ASE_%28Advanced_Silicon_Etch%29) |
| **ICP Metal etcher:**AlTiCrSi nano etch with zep resist | Jonas M. Lindhard @ danchip | [Specific Process Knowledge/Etch/ICP Metal Etcher](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher)[Specific Process Knowledge/Etch/ICP Metal Etcher/Aluminium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/Aluminium)[Specific Process Knowledge/Etch/ICP Metal Etcher/Titanium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/Titanium)[Specific Process Knowledge/Etch/ICP Metal Etcher/Chromium](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/Chromium)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano/nanoetch/180nmzep](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano/nanoetch/180nmzep)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano/nanoetch/340nmzep](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano/nanoetch/340nmzep)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano/nanoetch/211nmzep](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano/nanoetch/211nmzep)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano/Sinano3](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano/Sinano3)[Specific Process Knowledge/Etch/ICP Metal Etcher/silicon/nano/Sinano31](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/ICP_Metal_Etcher/silicon/nano/Sinano31) |
| **Wet SiO2 etch** | Karen Birkelund @danchip | [Specific Process Knowledge/Etch/Wet Silicon Oxide Etch (BHF)](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Wet_Silicon_Oxide_Etch_%28BHF%29) |
| **Customer satisfaction survey** | Mette Noer @ danchip | [November 2012 Survey](http://labadviser.danchip.dtu.dk/index.php/November_2012_Survey) |
| **Customer meeting December 2012** | Anders M. Jørengen @ danchip | <http://labadviser.danchip.dtu.dk/index.php/LabAdviser> |